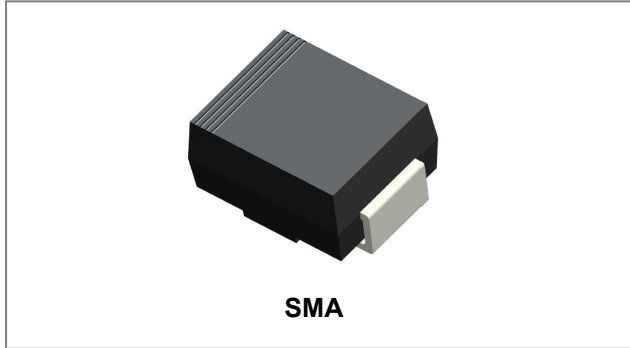


## RS1A-RS1M SURFACE MOUNT SUPER FAST RECTIFIER



### Features

- Fast switching for high efficiency
- Low Power Loss, High Efficiency
- High current capability
- Low reverse leakage
- For Use in Low Voltage Application
- Plastic Case Material has UL Flammability Classification Rating 94V-0
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

### Circuit Diagram



### Mechanical Data

- Case: SMA molded plastic body
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any
- Weight: 0.06 grams

### Maximum Ratings and Electrical Characteristics @T<sub>A</sub>=25°C unless otherwise specified

Type Number	Symbol	RS1A	RS1B	RS1D	RS1G	RS1J	RS1K	RS1M	Units	
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>									
Working Peak Reverse Voltage	V <sub>RWM</sub>	50	100	200	400	600	800	1000	V	
DC Blocking Voltage	V <sub>DC</sub>									
RMS Reverse Voltage	V <sub>RMS</sub>	35	70	140	280	420	560	700	V	
Average forward rectified output current @T <sub>L</sub> = 100°C	I <sub>O</sub>	1.0							A	
Total Device Dissipation Derate above 25°C		1.25 10							W mW/°C	
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	30							A	
Forward Voltage @I <sub>F</sub> = 1.0A	V <sub>F</sub>	1.3							V	
Peak Reverse Current @T <sub>A</sub> = 25°C	I <sub>RM</sub>	5.0							μA	
At Rated DC Blocking Voltage @T <sub>A</sub> = 125°C		200								
Maximum Reverse Recovery Time (Note 1)	T <sub>rr</sub>	150				250	500		ns	
Typical Junction Capacitance (Note 2)	C <sub>J</sub>	7							pF	
Typical Thermal Resistance Junction to Ambient (Note 3)	R <sub>θJA</sub> R <sub>θJL</sub>	100 32								°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150							°C	

Note: 1. Reverse recovery condition I<sub>F</sub>=0.5A, I<sub>R</sub>=1.0A, I<sub>rr</sub>=0.25A  
 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
 3. Device mounted on FR-4 substrate, 1"×1", 2oz, single-sided, PC boards with 0.1"×0.15" copper pad.

- China - Germany - Korea - Singapore - United States •
- <http://www.smc-diodes.com> - [sales@smc-diodes.com](mailto:sales@smc-diodes.com) •

**Ratings and Characteristics Curves**

Fig. 1 Forward Current Derating Curve

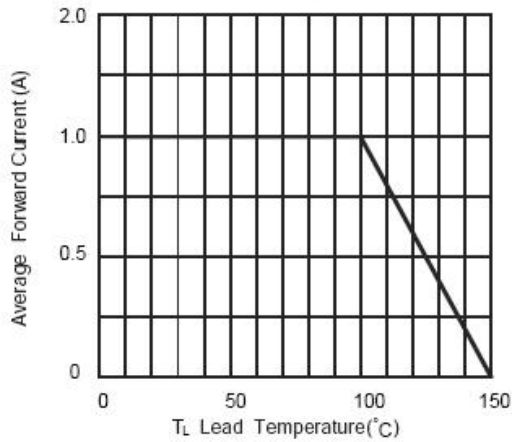


Fig. 2 Typ. Forward Characteristics

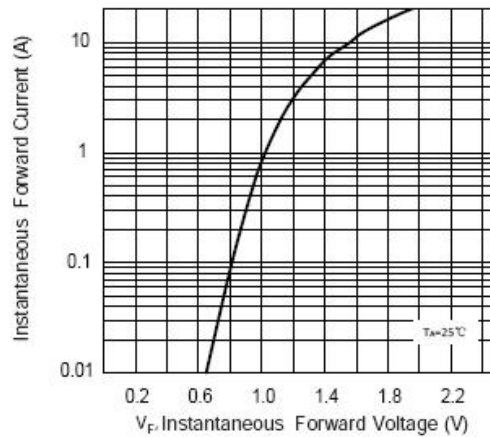


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

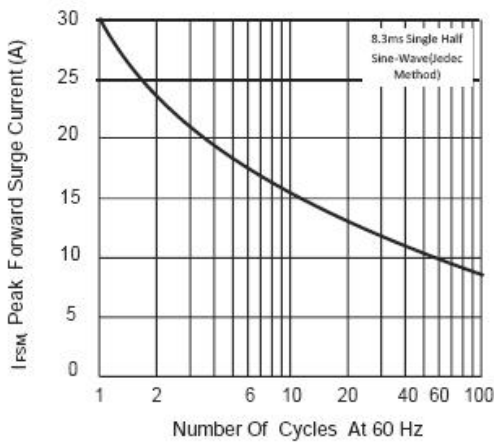


Fig. 4 Typical Junction Capacitance

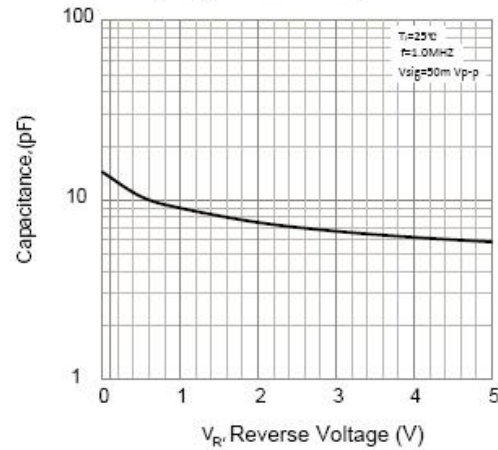


Fig. 5 Typical Reverse Characteristics

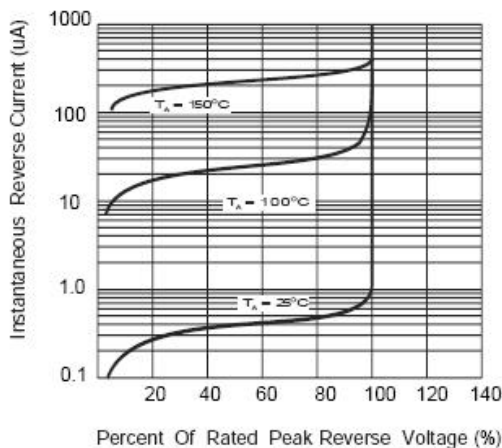
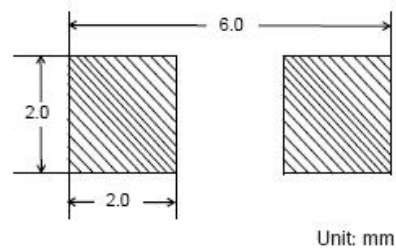
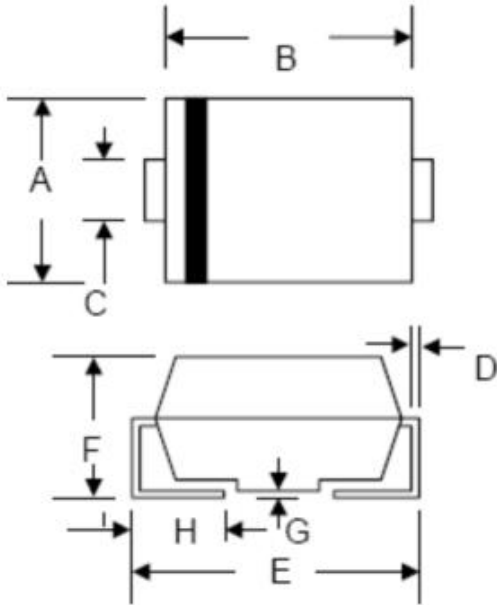


Fig. 6 Reflow Solder PAD Layout



**Mechanical Dimensions SMA**



SYMBOL	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.40	2.84	0.094	0.112
B	3.99	4.75	0.157	0.187
C	1.05	1.70	0.041	0.067
D	0.15	0.51	0.006	0.020
E	4.80	5.66	0.189	0.223
F	1.90	2.95	0.075	0.116
G	0.05	0.203	0.002	0.008
H	0.76	1.52	0.030	0.600

**Ordering Information**

Device	Package	Shipping
RS1A-RS1M	SMA (Pb-Free)	5000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

**Marking Diagram**

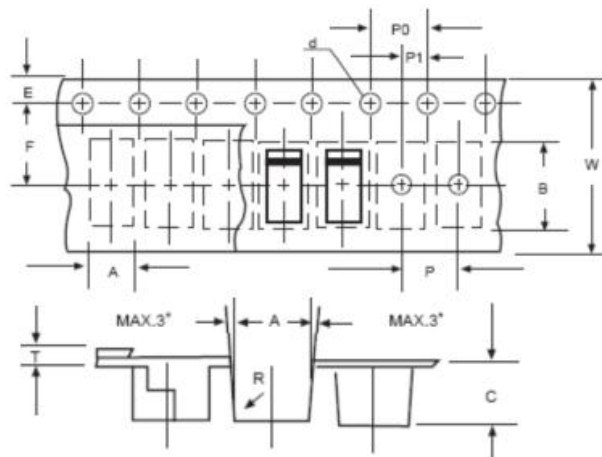


Where XXXXX is YYWWL

RS1A = Type Number  
YY = Year  
WW = Week  
L = Lot Number

**Cautions:** Molding resin  
Epoxy resin UL:94V-0

**Carrier Tape Specification SMA**



SYMBOL	Millimeters	
	Min.	Max.
A	2.97	3.17
B	5.70	5.90
C	2.32	2.52
d	1.40	1.60
E	1.40	1.60
F	5.60	5.70
P	3.90	4.10
P0	3.90	4.10
P1	1.90	2.10
T	0.25	0.35
W	11.80	12.20

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